

**Product / Package Information**

Package	LFCSP - Punched
Body Size (mm)	10 X 10 X 0.85 (7.3 EP)
Lead Count	72
Terminal Finish	100 Sn
MS Number	MS011269A

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.45E-01	86.9	869100	51.10		510965
Thermosets	Epoxy & Phenol Resin	Proprietary	2.13E-02	12.8	127800	7.51		75137
Other inorganic materials	Carbon black	1333-86-4	5.17E-04	0.3	3100	0.18		1823
Subtotal			1.67 E-01	100.00	1000000	58.79		587925

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	9.90 E-02	97.5	975000	34.91		349062
Copper & its alloys	Iron	7439-89-6	2.39 E-03	2.35	23500	0.84		8413
Copper & its alloys	Zinc	7440-66-6	1.22 E-04	0.12	1200	0.04		430
Copper & its alloys	Phosphorus	7723-14-0	3.05 E-05	0.03	300	0.01		107
Subtotal			1.02 E-01	100.00	1000000	35.80		358013

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	9.98 E-04	100.0	1000000	0.35		3520

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	3.23 E-03	100.0	1000000	1.14		11388

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	1.74 E-03	100.0	1000000	0.61		6131

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	8.30 E-03	100.0	1000000	2.93		29268

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	7.84 E-04	73.54	735400	0.28		2763
Other organic materials	Epoxy resin A	TS ref# 10013	7.83 E-05	7.35	73500	0.03		276
Others	Anhydride	TS ref# 10181	7.83 E-05	7.35	73500	0.03		276
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.13 E-05	2.94	29400	0.01		110
Other organic materials	Epoxy resin B	TS ref# 10237	3.13 E-05	2.94	29400	0.01		110
Others	Epoxy resin modifier	TS ref# 10038	3.13 E-05	2.94	29400	0.01		110
Others	Anhydride	TS ref# 10180	3.13 E-05	2.94	29400	0.01		110
Subtotal			1.07 E-03	100.0	1000000	0.38		3756

<b>Package Totals</b>			<b>Weight (g)</b> 2.84 E-01			<b>Percentage (%)</b> 100		<b>PPM</b> 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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